



# CALL FOR PAPERS

## SEVENTH INTERNATIONAL SYMPOSIUM ON

# **SILANES** AND OTHER COUPLING AGENTS

To be held July 15-18, 2009; University of Maine, Orono, Maine, USA

This symposium continues the tradition set by the first symposium in this series: "Silanes and Other Coupling Agents" which was hosted in 1991 by the Dow Corning Corporation in honor of Dr. Edwin P. Plueddemann. As with its predecessors, this symposium will be concerned with the technological areas where the use of surface primers such as silanes is critical to the success of many technologies.

We are indeed happy to announce that this the 7<sup>th</sup> symposium in the series will be organized in collaboration with Prof. Douglas Gardner in the Advanced Engineered Wood Composites Center at the University of Maine, Orono, Maine. Prof. Gardner is well acquainted with problems of adhesion and coupling agents as applied to wood composites and is also serving on the editorial board of the Journal of Adhesion Science and Technology which is edited by the Conference Director Dr. Mittal. Prof. Gardner and his group look forward to hosting this symposium and greeting all participants from both academia and

industry from all corners of the globe.

Historically the silanes have been used as coupling agents for thin films in the microelectronics industry and in glass fiber composites where the use of silanes has been an enabling factor in the success of many manufactured products. Quite surprisingly, silanes have also found a role in biotechnology as specific coupling agents for bonding polynucleotides to the so-called "gene chips" and also in cosmetic applications. This symposium is organized to bring together scientists, technologists and engineers interested in all aspects of coupling agent technology, to review and assess the current state of knowledge, to provide a forum for exchange and cross-fertilization of ideas and to define problem areas which need intensified efforts. The invited speakers have been selected so as to represent widely differing disciplines and interests, and they hail from academic, governmental and industrial research laboratories. This meeting is planned to be a truly international event with participation from research groups from academia and industry worldwide.

### AMONG TOPICS TO BE COVERED ARE:

- ▶ Mechanisms of silanes action.
- ▶ Role of silanes in adhesion of coatings, composites and adhesive joints.
- ▶ Deposition techniques:
  - solution
  - plasma
  - vapor
  - electrochemical
- ▶ Non-silane adhesion promoters.
- ▶ Plasma polymerized coatings as adhesion promoters.
- ▶ Relevance of silanes in durability of bonds.
- ▶ Applications:
  - coatings, corrosion inhibitors
  - adhesive joints, composites
  - biological applications: dental, gene chip cosmetics
- ▶ Silane surface characterization.
  - Standard: contact angle, FTIR,...
  - Advanced: neutron scattering, ...

This symposium is being organized by MST Conferences under the direction of Dr. K. L. Mittal, Editor, Journal of Adhesion Science and Technology (JAST) and in collaboration with Prof. Douglass Gardner at the University of Maine. It is planned to publish the proceedings of this symposium in the Journal of Adhesion Science and Technology, edited by the conference chairman Dr. Mittal. Please notify the conference chairman of your intentions to present a paper as early as possible. An abstract of about 200 words should be sent by **April 15, 2009** to the conference chairman by any of the following methods:

E-mail: [rhl@mstconf.com](mailto:rhl@mstconf.com)  
 FAX: 212-656-1016  
 Regular mail:

Dr. Robert H. Lacombe  
 Conference Chairman  
 3 Hammer Drive  
 Hopewell Junction, NY 12533

Contact by phone: 845-897-1654; 845-227-7026  
 Full conference details and registration via the Internet will be maintained on our web site:

<http://mstconf.com/silanes7.htm>

Or mail response form below to the conference chairman at the address above.

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I PLAN TO:

- ATTEND
- PRESENT A PAPER

TENTATIVE TITLE: \_\_\_\_\_

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